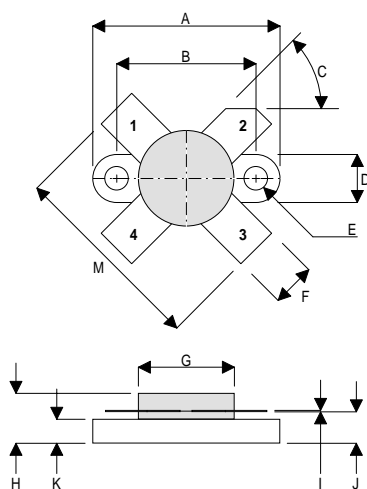


MECHANICAL DATA



DM

PIN 1 SOURCE PIN 2 DRAIN
 PIN 3 SOURCE PIN 4 GATE

DIM	mm	Tol.	Inches	Tol.
A	24.76	0.13	0.975	0.005
B	18.42	0.13	0.725	0.005
C	45°	5°	45°	5°
D	6.35	0.13	0.25	0.005
E	3.17 Dia.	0.13	0.125 Dia.	0.005
F	5.71	0.13	0.225	0.005
G	12.7 Dia.	0.13	0.500 Dia.	0.005
H	6.60	REF	0.260	REF
I	0.13	0.02	0.005	0.001
J	4.32	0.13	0.170	0.005
K	3.17	0.13	0.125	0.005
M	26.16	0.25	1.03	0.010

**GOLD METALLISED
 MULTI-PURPOSE SILICON
 DMOS RF FET
 80W – 28V – 175MHz
 SINGLE ENDED**

FEATURES

- SIMPLIFIED AMPLIFIER DESIGN
- SUITABLE FOR BROAD BAND APPLICATIONS
- LOW C_{rss}
- SIMPLE BIAS CIRCUITS
- LOW NOISE
- HIGH GAIN – 16 dB MINIMUM

APPLICATIONS

- HF/VHF COMMUNICATIONS
 from 1 MHz to 175 MHz

ABSOLUTE MAXIMUM RATINGS ($T_{case} = 25^{\circ}C$ unless otherwise stated)

P_D	Power Dissipation	146W
BV_{DSS}	Drain – Source Breakdown Voltage	70V
BV_{GSS}	Gate – Source Breakdown Voltage	$\pm 20V$
$I_{D(sat)}$	Drain Current	20A
T_{stg}	Storage Temperature	-65 to $150^{\circ}C$
T_j	Maximum Operating Junction Temperature	$200^{\circ}C$

ELECTRICAL CHARACTERISTICS ($T_{case} = 25^{\circ}C$ unless otherwise stated)

Parameter	Test Conditions	Min.	Typ.	Max.	Unit
BV_{DSS} Drain-Source Breakdown Voltage	$V_{GS} = 0$ $I_D = 100mA$	70			V
I_{DSS} Zero Gate Voltage Drain Current	$V_{DS} = 28V$ $V_{GS} = 0$			2	mA
I_{GSS} Gate Leakage Current	$V_{GS} = 20V$ $V_{DS} = 0$			1	μA
$V_{GS(th)}$ Gate Threshold Voltage *	$I_D = 10mA$ $V_{DS} = V_{GS}$	1		7	V
g_{fs} Forward Transconductance *	$V_{DS} = 10V$ $I_D = 4A$	3.2			S
G_{PS} Common Source Power Gain	$P_O = 80W$	16			dB
η Drain Efficiency	$V_{DS} = 28V$ $I_{DQ} = 0.4A$	50			%
VSWR Load Mismatch Tolerance	$f = 175MHz$	20:1			—
C_{iss} Input Capacitance	$V_{DS} = 0$ $V_{GS} = -5V$ $f = 1MHz$			240	pF
C_{oss} Output Capacitance	$V_{DS} = 28V$ $V_{GS} = 0$ $f = 1MHz$			100	pF
C_{rss} Reverse Transfer Capacitance	$V_{DS} = 28V$ $V_{GS} = 0$ $f = 1MHz$			10	pF

* Pulse Test: Pulse Duration = 300 μs , Duty Cycle $\leq 2\%$

HAZARDOUS MATERIAL WARNING

The ceramic portion of the device between leads and metal flange is beryllium oxide. Beryllium oxide dust is highly toxic and care must be taken during handling and mounting to avoid damage to this area.

THESE DEVICES MUST NEVER BE THROWN AWAY WITH GENERAL INDUSTRIAL OR DOMESTIC WASTE.

THERMAL DATA

$R_{THj-case}$	Thermal Resistance Junction – Case	Max. 1.2°C / W
----------------	------------------------------------	----------------

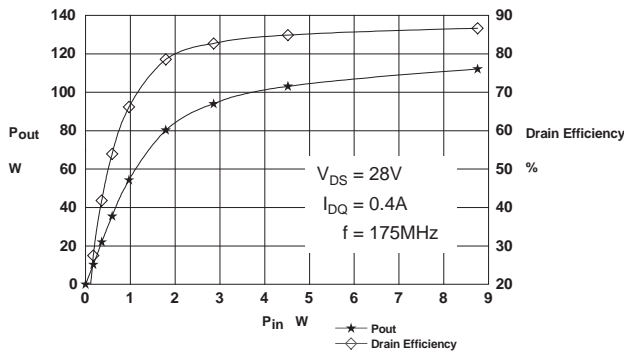


Figure 1 – Power Output and Efficiency vs. Power Input.

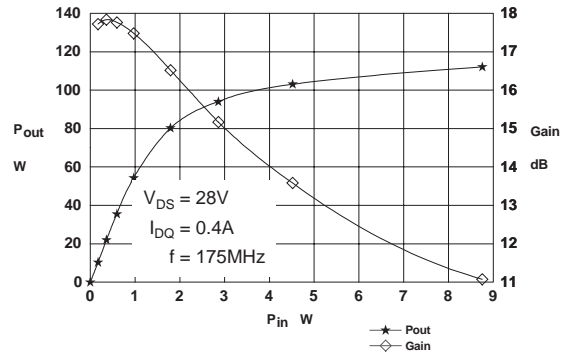


Figure 2 – Power Output & Gain vs. Power Input.

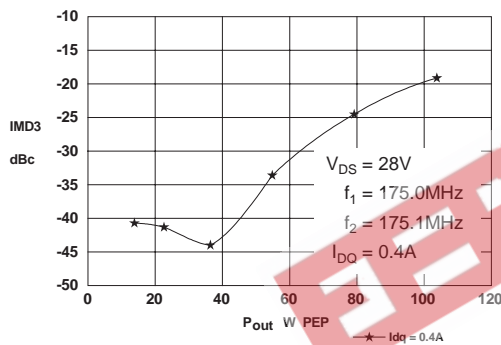


Figure 3 – IMD vs. Output Power.

**D1005UK
OPTIMUM SOURCE AND LOAD IMPEDANCE**

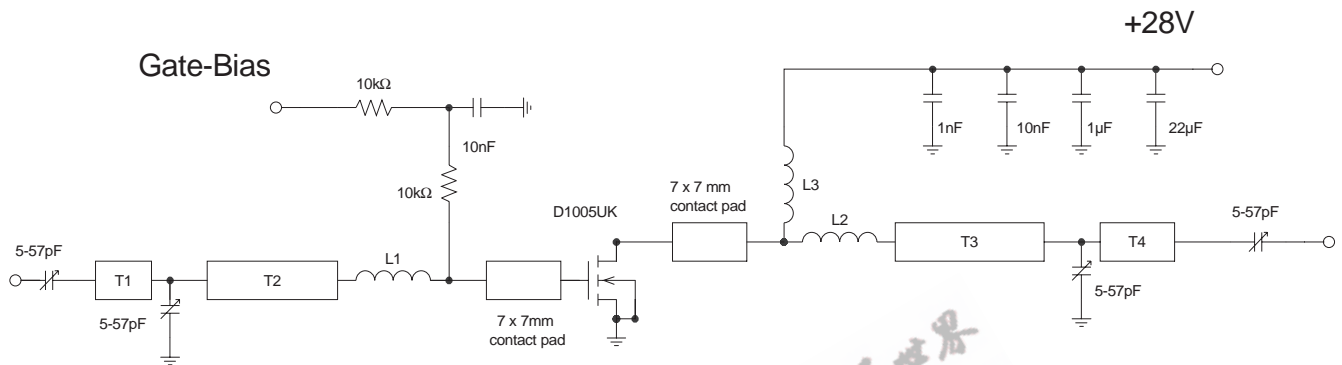
Frequency MHz	Z _S Ω	Z _L Ω
175MHz	3 + j1	3 - j2.5

Typical S Parameters

! V_{DS} = 28V, I_{DQ} = 0.3A

MHz S M A R 50

!Freq MHz	S11 mag ang	S21 mag ang	S12 mag ang	S22 mag ang
50	0.95 -58	4.29 94	0.006 34	0.66 -162
100	0.94 -79	3.32 81	0.006 57	0.75 -164
150	0.94 -104	2.26 65	0.01 98	0.84 -169
200	0.93 -124	1.59 53	0.019 107	0.88 -175
250	0.94 -140	1.2 41	0.031 103	0.92 -180
300	0.95 -152	0.94 34	0.042 102	0.93 176
350	0.96 -161	0.72 22	0.052 92	0.96 170
400	0.96 -169	0.59 19	0.064 91	0.98 164
450	0.97 -177	0.46 11	0.073 84	1.00 159
500	0.98 177	0.35 -2	0.091 82	1.00 154



D1005UK 175MHz TEST FIXTURE

Substrate 1.6mm PTFE/ glass, Er= 2.5
All microstrip lines W= 4.4mm

T1 8mm
T2 22mm
T3 18mm
T4 4.5mm

L1 Hairpin loop 16swg 15.5mm dia
L2 Hairpin loop 16swg 10mm dia
L3 11 turns 18swg enamelled copper wire, 10mm i.d.